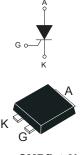


X0115MUF

Datasheet

1 A sensitive gate SCR thyristor



SMBflat-3L

Features

- On-state rms current, 1 A
- Narrow sensitive gate current from 30 μA to 150 μA
- Repetitive peak off-state voltage, 600 V
- Non-repetitive surge peak off-state voltage, 750 V
- Compact and ultraflat SMBflat-3L package with creepage distance of 3.4 mm

Applications

- Ground-fault circuit interrupter (GFCI, RCB, RCD)
- Arc-fault circuit interrupter (AFCI)
- Overvoltage crowbar protection in power supplies
- Capacitive ignition circuits
- Low consumption triggering switches

Description

Thanks to highly sensitive triggering levels, the 1 A X0115MUF SCR thyristor is suitable for all applications where available gate current is limited. The X0115MUF offers a high blocking voltage of 600 V, and a surge peak voltage of 750 V, ideal for applications like ground fault circuit interrupter (GFCI) and arc fault circuit interrupters (AFCI).

The surface mount SMBflat-3L package allows modern, compact, SMD based designs for automated manufacturing. Its 3.4 mm creepage distance guarantees a 250 V functional isolation (UL 840) at a level 2 pollution degree.

Product status link			
X0115MUF			
Product summary			
I _{T(RMS)} 1 A			
V _{DRM} /V _{RRM}	600 V		
T _{j(max.)}	125 °C		

1 Characteristics

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Symbol	Value	Unit			
I _{T(RMS)}	On-state RMS current (180° conduction angle)			1	А
I _{T(AV)}	Average on-state current (180° conduction angle)			0.64	А
	Non repetitive surge peak on-state current $t_p = 8.3 \text{ ms}$		T _i = 25 °C	12	
ITSM	(T _j initial = 25 °C)	t _p = 10 ms	1j = 25°C	11	A
l ² t	$I^{2}t$ value for fusing $t_{p} = 10 \text{ ms}$		T _j = 25 °C	0.60	A ² s
dl/dt	Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$, $t_r \le 100$ ns F = 60 Hz		T _j = 25 °C	75	A/µs
V _{DRM} / V _{RRM}	Repetitive peak off-state voltage $T_j = 125 \text{ °C}$				V
V _{DSM} / V _{RSM}	Non repetitive surge peak off-state voltage $t_p = 10 \text{ ms}$		T _j = 25 °C	750	V
I _{GM}	Peak forward gate current $t_p = 20 \ \mu s$ $T_j = 1$			1.2	Α
P _{G(AV)}	Average gate power dissipation	0.2	W		
T _{stg}	Storage junction temperature range	-40 to +150	°C		
Tj	Operating junction temperature range			-40 to +125	°C

Table 1. Absolute maximum ratings (limiting values)

Table 2. Electrical characteristics (T_j = 25 °C, unless otherwise specified)

Symbol	Parameters	Va	Unit	
		Min.	30	μΑ
I _{GT}	V_{D} = 12 V, R _L = 140 Ω	Max.	150	
V _{GT}		Max.	0.8	V
V_{GD}	$V_D = V_{DRM}$, $R_L = 3.3 \text{ k}\Omega$, $R_{GK} = 1 \text{ k}\Omega$, $T_j = 125 \text{ °C}$		0.2	V
V _{RG}	I _{RG} = 10 μA		5	V
Ι _Η	I _T = 50 mA, R _{GK} = 1 kΩ		5	mA
١L	$I_G = 1.2 I_{GT}, R_{GK} = 1 k\Omega$		6	mA
dV/dt	V_D = 67 % V_{DRM} , R_{GK} = 1 k Ω , T_j = 125 °C	Min.	80	V/µs

Table 3. Static characteristics

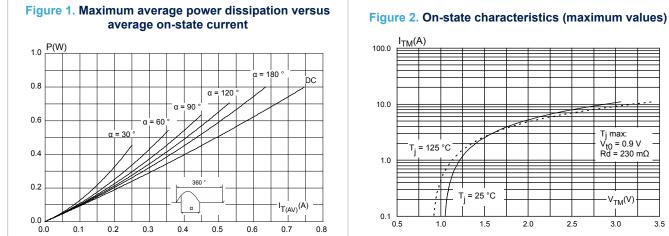
Symbol	Symbol Test conditions			Value	
V _T	I _{TM} = 2.0 A, t _p = 380 μs	T _j = 25 °C	Max.	1.40	V
V _{TO}	Threshold on-state voltage	T _j = 125 °C	Max.	0.90	V
R _d	Dynamic resistance	T _j = 125 °C	Max.	230	mΩ
I _{DRM} / I _{RRM}	$V_D = V_{DRM}, V_R = V_{RRM}, R_{GK} = 1 k\Omega$	T _j = 25 °C		1	μA
		T _j = 125 °C	Max.	150	μA

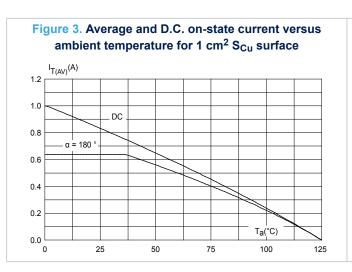
Table 4. Thermal resistance

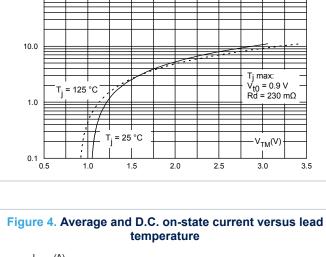
Symbol	Parameters	Value	Unit
R _{th(j-l)}	Junction to lead (DC)	15	°C/W
R _{th(j-a)}	Junction to ambient (DC) for 5 cm ² copper surface	75	0/00

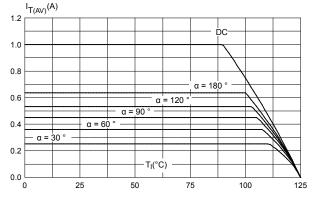
1.1 **Characteristics (curves)**

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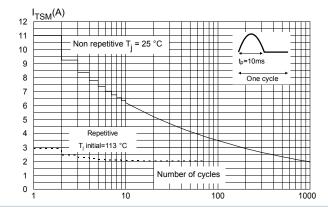
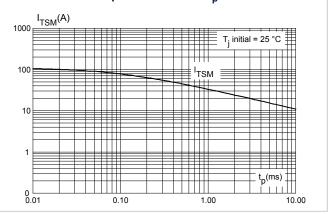


Figure 6. Non repetitive surge peak on-state current for a sinusoidal pulse with width t_p < 10 ms





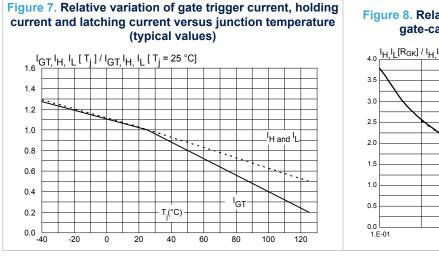


Figure 8. Relative variation of holding current versus gate-cathode resistance (typical values)

Figure 9. Relative variation of static dV/dt immunity versus junction temperature

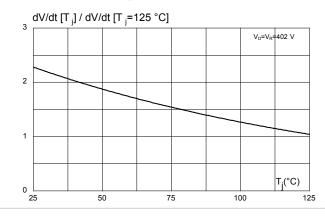
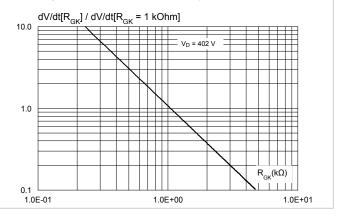
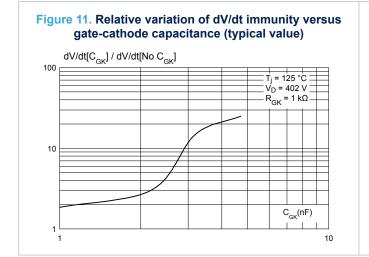
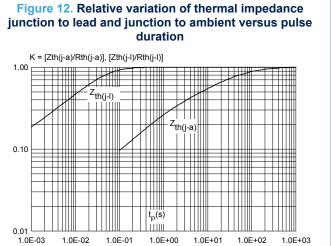


Figure 10. Relative variation of dV/dt immunity versus gate-cathode resistance (typical values)







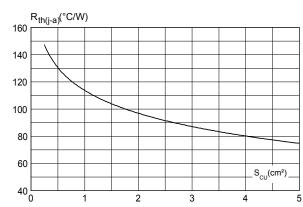


Figure 13. Typical thermal resistance junction to ambient versus copper surface under anode (epoxy FR4, e_{CU} = 35 µm, SMBflat-3L)

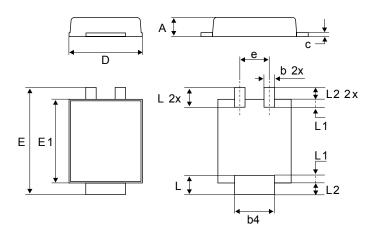
2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

2.1 SMBflat-3L package information

- Epoxy meets UL94, V0
- Lead-free package

Figure 14. SMBflat-3L package outline



Note: This package drawing may slightly differ from the physical package. However, all the specified dimensions in the following table are guaranteed.

Table 5. SMBflat-3L mechanical data

	Dimensions					
Ref.		Millimeters		Inches (dimensions are for reference only)		
	Min.	Тур.	Max.	Min.	Тур.	Max.
A	0.90		1.10	0.0354		0.0433
b	0.35		0.65	0.0138		0.0256
b4	1.95		2.20	0.0768		0.0866
С	0.15		0.40	0.0059		0.0157
D	3.30		3.95	0.1299		0.1555
E	5.10		5.60	0.2008		0.2205
E1	4.05		4.60	0.1594		0.1811
L	0.75		1.50	0.0295		0.0591
L1		0.40			0.0157	
L2		0.60			0.0236	
е		1.60			0.0630	

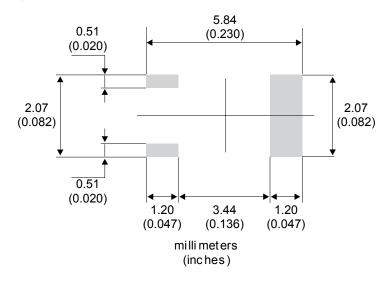


Figure 15. Footprint recommendations, dimensions in mm (inches)

Note: This drawing may not be in scale; however, all the specified dimensions are guaranteed.



3 Ordering information

Figure 16. Ordering information scheme

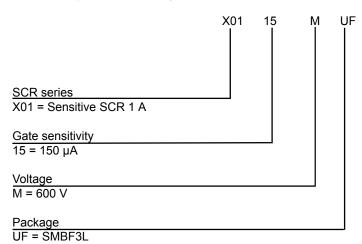


Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
X0115MUF	X1M	SMBflat-3L	47 mg	5000	Tape and reel

Revision history

Table 7. Document revision history

Date	Revision	Changes
30-Jul-2019	1	First issue.
10-Oct-2019	2	Updated Table 2. Electrical characteristics (T_j = 25 °C, unless otherwise specified).



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